

ABSTRACT

A printed circuit board assembly adapted for immersion cooling is disclosed. The assembly includes a first circuit board having a first device side with a first portion configured to mount a first plurality of semiconductor devices. A second circuit board having a second device side with a second portion configured to mount a second plurality of semiconductor devices is disposed in confronting parallel relationship to the first circuit board. The assembly further includes a border element interposed between the first and second boards and disposed around the respective first and second portions. The border element cooperates with the first and second boards to form a liquid-tight container. An inlet formed in the border receives an electrically nonconducting liquid that is subsequently discharged through an outlet.

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